

I-T Characteristics / 時間-電流特性

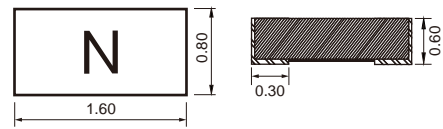
| Ampere Rating 額定電流 | % of Ampere Rating 額定電流百分比 | Opening Time 熔斷時間 |
|-----------------------|-------------------------------|--|
| 1A~6A | 100% | 4 Hrs Min. / 最短4小時 |
| | 200% | 120s Max. / 最長120秒 |
| | 300% | 3s Max. / 最長3秒 |
| 1A~1.5A | 800% | 0.5ms Min. 50ms Max. / 最短0.5毫秒, 最長50毫秒 |
| 2A~6A | | 1ms Min. 50ms Max. / 最短1毫秒, 最長50毫秒 |



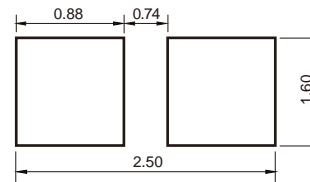
Product Features / 產品特性

| | |
|---|---|
| Materials 材質 | Body / 本體 : Cu / 銅, Sn / 錫 Substrate / 基板: alumina ceramic / 氧化鋁陶瓷基板 Electrode / 電極: Cu / 銅, Ni / 鎳, Sn / 錫 (termination with nickel and Pure-tin solder plating / 電極端面為鍍鎳及無鉛錫) |
| Operating Temperature 操作溫度 | -55°C to +150°C (consider de-rating / 需考慮溫度折減) |
| Solderability 可焊性 | T / 熔錫溫度=235°C±5°C, t / 浸錫時間=2+0/-0.5s, Cover / 覆蓋率 ≥95%, ΔS=2.0mm±0.5mm, magnifier: 20X |
| Resistance to Soldering Heat 耐焊接熱 | T / 熔錫溫度=260°C±5°C, t / 浸錫時間=10s ±1s ΔS=2.0mm±0.5mm |
| Recommended Soldering Parameters 建議錫參數 | 260°C, 10s Max. (compatible with both wave and solder-reflow / 可用于波峰焊和回流焊制程) |
| Storage Conditions 儲存條件 | Can be stored for 3 years under tight seal condition at temperature of +10°C~40°C, relative humidity ≤ 75%. 在溫度+10°C~40°C, 相對濕度 ≤ 75% 的密閉條件下可存放 2 年。 At most can be kept 30 days at temperature +10°C~40°C, relative humidity ≤ 95% under covered conditions. 在溫度+10°C~40°C, 相對濕度為 95% 的非露天最多可存放 30 天。 |

Dimensions / 尺寸圖 (Unit / 單位:mm)



Recommended Pad Layout



Electrical Characteristics / 電氣特性

| Rated Current 額定電流 | Rated Voltage 額定電壓 | Breaking Capacity 分斷能力 | Safety Approvals 安全認證 |
|-----------------------|-----------------------|---------------------------|-----------------------|
| | | | |
| 1.00A | 32V DC | 1A~6A 50A@32V DC | ● |
| 1.50A | 32V DC | | ● |
| 2.00A | 32V DC | | ● |
| 2.50A | 32V DC | | ● |
| 3.00A | 32V DC | | ● |
| 3.50A | 32V DC | | ● |
| 4.00A | 32V DC | | ● |
| 5.00A | 32V DC | | ● |
| 6.00A | 32V DC | | ● |

单击下面可查看定价，库存，交付和生命周期等信息

[>>Walter\(华德\)](#)